

/ Revised record

A	2022-6-13				

/ Descriptions

SOT23-6 TVS
Low Capacitance TVS Array in a SOT23-6 Plastic Package.

/ Features

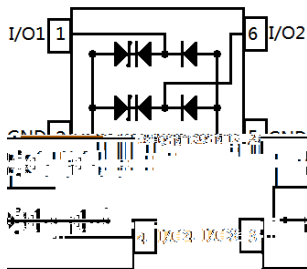
4 ESD I/O 0.35pF

4 ESD protection structures, low capacitance for high-speed interfaces, Capacitance I / O channel is not more than 0.35pF, Low clamping voltage, Low operating voltage, suitable for high speed data transmission lines. HF Product.

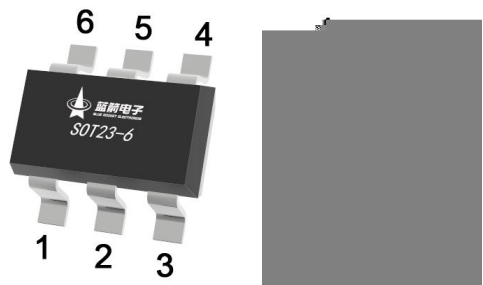
/ Applications

ESD USB 2.0 IEC 61000-4-2(ESD) 30kV (), ±20kV ()
ESD protection for high-speed data lines, such as USB 2.0, set-top boxes, monitors and so on.
According to IEC 61000-4-2 (ESD) Standard: ± 30kV (air discharge), ± 20kV (contact discharge).

/ Equivalent Circuit



/ Pinning

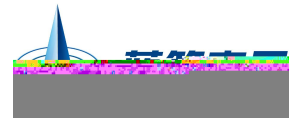


/ Marking

See Marking Instructions.

BRES5V0X4C6MF

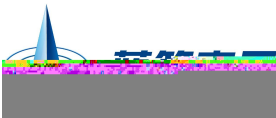
Rev.A Jun.-2022



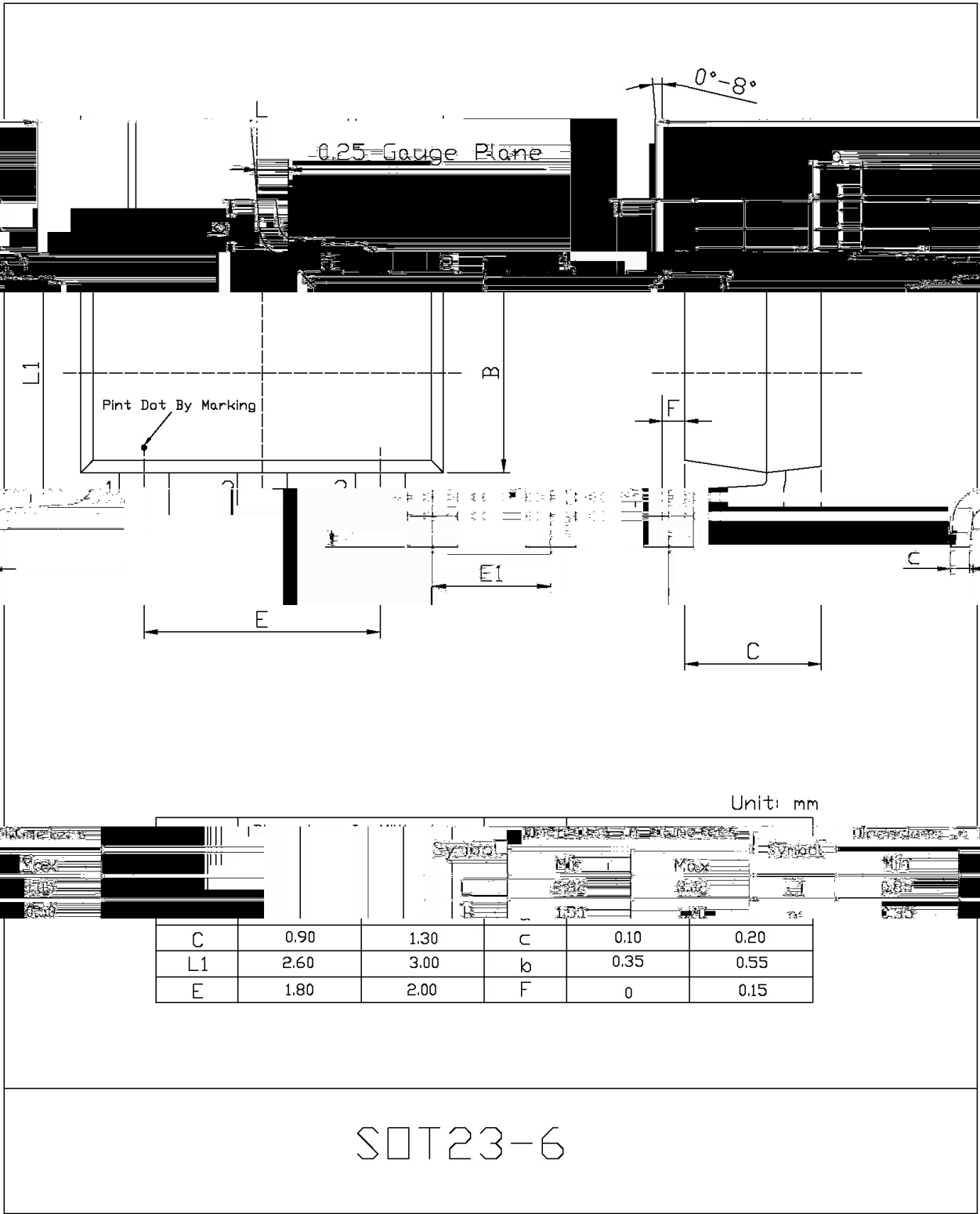
DATA SHEET

Parameter	Symbol	Rating	Unit
Peak Pulse Power (tp = 8/20μs)	P _{PP}	56	W
Peak Pulse Current (tp = 8/20μs)	I _{PP}	4.0	A

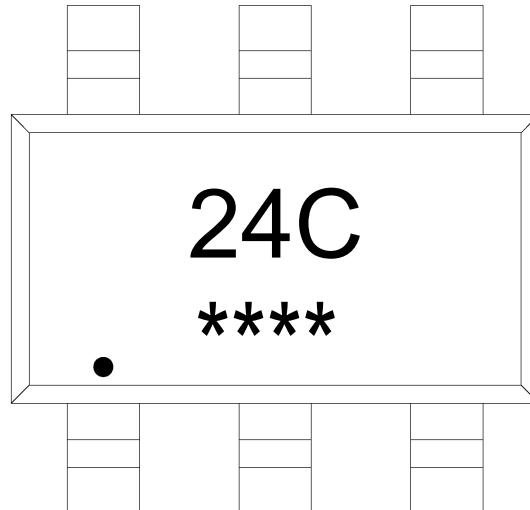
ESD per IEC 61000-4-



/ Package Dimensions



/ Marking Instructions



说明：

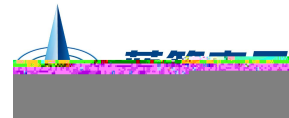
24C： 为型号代码

****： 为生产批号代码，随生产批号变化

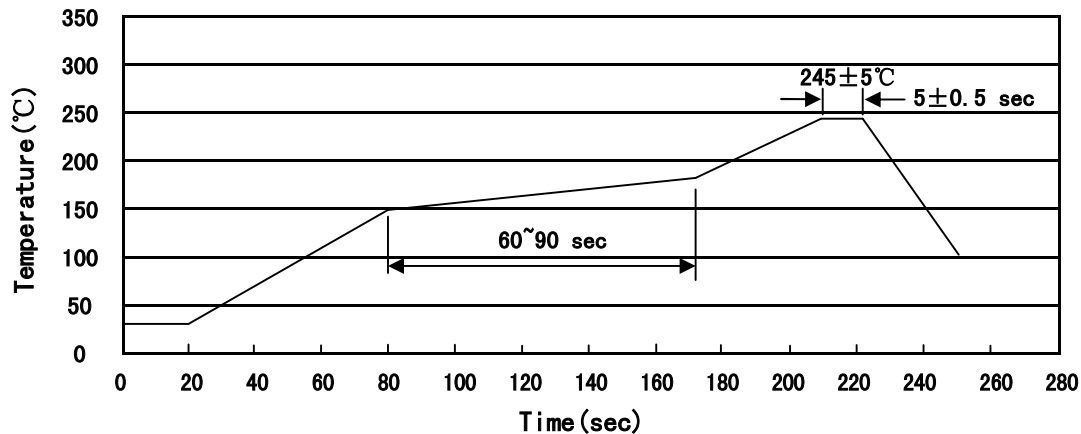
Note:

24C: Product Type Code

****: Lot No. Code, code change with Lot No



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|--|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | | 2 | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT23-5/6	3,000	10	30,000	4	120,000	7" ×8	210×205×205	445×230×435

/ Notices